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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	32MHz
Connectivity	LINbus, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	18
Program Memory Size	14KB (8K x 14)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 12x10b; D/A 1x5b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SOIC (0.295", 7.50mm Width)
Supplier Device Package	20-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lf1579-e-so

TABLE 3-9: PIC16(L)F1574/5/8/9 MEMORY MAP, BANKS 16-23

BANK16		BANK17		BANK18		BANK19		BANK20		BANK21		BANK22		BANK23	
800h	Core Registers (Table 3-2)	880h	Core Registers (Table 3-2)	900h	Core Registers (Table 3-2)	980h	Core Registers (Table 3-2)	A00h	Core Registers (Table 3-2)	A80h	Core Registers (Table 3-2)	B00h	Core Registers (Table 3-2)	B80h	Core Registers (Table 3-2)
80Bh		88Bh		90Bh		98Bh		A0Bh		A8Bh		B0Bh		B8Bh	
80Ch	—	88Ch	—	90Ch	—	98Ch	—	A0Ch	—	A8Ch	—	B0Ch	—	B8Ch	—
80Dh	—	88Dh	—	90Dh	—	98Dh	—	A0Dh	—	A8Dh	—	B0Dh	—	B8Dh	—
80Eh	—	88Eh	—	90Eh	—	98Eh	—	A0Eh	—	A8Eh	—	B0Eh	—	B8Eh	—
80Fh	—	88Fh	—	90Fh	—	98Fh	—	A0Fh	—	A8Fh	—	B0Fh	—	B8Fh	—
810h	—	890h	—	910h	—	990h	—	A10h	—	A90h	—	B10h	—	B90h	—
811h	—	891h	—	911h	—	991h	—	A11h	—	A91h	—	B11h	—	B91h	—
812h	—	892h	—	912h	—	992h	—	A12h	—	A92h	—	B12h	—	B92h	—
813h	—	893h	—	913h	—	993h	—	A13h	—	A93h	—	B13h	—	B93h	—
814h	—	894h	—	914h	—	994h	—	A14h	—	A94h	—	B14h	—	B94h	—
815h	—	895h	—	915h	—	995h	—	A15h	—	A95h	—	B15h	—	B95h	—
816h	—	896h	—	916h	—	996h	—	A16h	—	A96h	—	B16h	—	B96h	—
817h	—	897h	—	917h	—	997h	—	A17h	—	A97h	—	B17h	—	B97h	—
818h	—	898h	—	918h	—	998h	—	A18h	—	A98h	—	B18h	—	B98h	—
819h	—	899h	—	919h	—	999h	—	A19h	—	A99h	—	B19h	—	B99h	—
81Ah	—	89Ah	—	91Ah	—	99Ah	—	A1Ah	—	A9Ah	—	B1Ah	—	B9Ah	—
81Bh	—	89Bh	—	91Bh	—	99Bh	—	A1Bh	—	A9Bh	—	B1Bh	—	B9Bh	—
81Ch	—	89Ch	—	91Ch	—	99Ch	—	A1Ch	—	A9Ch	—	B1Ch	—	B9Ch	—
81Dh	—	89Dh	—	91Dh	—	99Dh	—	A1Dh	—	A9Dh	—	B1Dh	—	B9Dh	—
81Eh	—	89Eh	—	91Eh	—	99Eh	—	A1Eh	—	A9Eh	—	B1Eh	—	B9Eh	—
81Fh	—	89Fh	—	91Fh	—	99Fh	—	A1Fh	—	A9Fh	—	B1Fh	—	B9Fh	—
820h	Unimplemented Read as '0'	8A0h	Unimplemented Read as '0'	920h	Unimplemented Read as '0'	9A0h	Unimplemented Read as '0'	A20h	Unimplemented Read as '0'	AA0h	Unimplemented Read as '0'	B20h	Unimplemented Read as '0'	BA0h	Unimplemented Read as '0'
86Fh		8EFh		96Fh		9EFh		A6Fh		AEFh		B6Fh		BEFh	
870h	Accesses 70h – 7Fh	8F0h	Accesses 70h – 7Fh	970h	Accesses 70h – 7Fh	9F0h	Accesses 70h – 7Fh	A70h	Accesses 70h – 7Fh	AF0h	Accesses 70h – 7Fh	B70h	Accesses 70h – 7Fh	BF0h	Accesses 70h – 7Fh
87Fh		8FFh		97Fh		9FFh		A7Fh		AFFh		B7Fh		BFFh	

Legend: = Unimplemented data memory locations, read as '0'.

TABLE 3-10: PIC16(L)F1574/5/8/9 MEMORY MAP, BANKS 24-31

BANK 24		BANK 25		BANK 26		BANK 27		BANK 28		BANK 29		BANK 30		BANK 31	
C00h	Core Registers (Table 3-2)	C80h	Core Registers (Table 3-2)	D00h	Core Registers (Table 3-2)	D80h	Core Registers (Table 3-2)	E00h	Core Registers (Table 3-2)	E80h	Core Registers (Table 3-2)	F00h	Core Registers (Table 3-2)	F80h	Core Registers (Table 3-2)
C0Bh		C8Bh		D0Bh		D8Bh		E0Bh		E8Bh		F0Bh		F8Bh	
C0Ch	—	C8Ch	—	D0Ch	—	D8Ch	See Table 3-11	E0Ch	See Table 3-12	E8Ch	See Table 3-12	F0Ch	—	F8Ch	See Table 3-13
C0Dh	—	C8Dh	—	D0Dh	—							F0Dh	—		
C0Eh	—	C8Eh	—	D0Eh	—							F0Eh	—		
C0Fh	—	C8Fh	—	D0Fh	—							F0Fh	—		
C10h	—	C90h	—	D10h	—							F10h	—		
C11h	—	C91h	—	D11h	—							F11h	—		
C12h	—	C92h	—	D12h	—							F12h	—		
C13h	—	C93h	—	D13h	—							F13h	—		
C14h	—	C94h	—	D14h	—							F14h	—		
C15h	—	C95h	—	D15h	—							F15h	—		
C16h	—	C96h	—	D16h	—							F16h	—		
C17h	—	C97h	—	D17h	—							F17h	—		
C18h	—	C98h	—	D18h	—							F18h	—		
C19h	—	C99h	—	D19h	—							F19h	—		
C1Ah	—	C9Ah	—	D1Ah	—							F1Ah	—		
C1Bh	—	C9Bh	—	D1Bh	—							F1Bh	—		
C1Ch	—	C9Ch	—	D1Ch	—							F1Ch	—		
C1Dh	—	C9Dh	—	D1Dh	—							F1Dh	—		
C1Eh	—	C9Eh	—	D1Eh	—							F1Eh	—		
C1Fh	—	C9Fh	—	D1Fh	—							F1Fh	—		
C20h	Unimplemented Read as ‘0’	CA0h	Unimplemented Read as ‘0’	D20h	Unimplemented Read as ‘0’							F20h	Unimplemented Read as ‘0’		
C6Fh		CEFh		D6Fh		DEFh		E6Fh		EEFh		F6Fh		FEFh	
C70h	Accesses 70h – 7Fh	CF0h	Accesses 70h – 7Fh	D70h	Accesses 70h – 7Fh	DF0h	Accesses 70h – 7Fh	E70h	Accesses 70h – 7Fh	EF0h	Accesses 70h – 7Fh	F70h	Accesses 70h – 7Fh	FF0h	Accesses 70h – 7Fh
CFFh		CFFh		D7Fh		DFFh		E7Fh		EFFh		F7Fh		FFFh	

Legend: = Unimplemented data memory locations, read as ‘0’

4.0 DEVICE CONFIGURATION

Device configuration consists of Configuration Words, Code Protection and Device ID.

4.1 Configuration Words

There are several Configuration Word bits that allow different oscillator and memory protection options. These are implemented as Configuration Word 1 at 8007h and Configuration Word 2 at 8008h.

Note:	The $\overline{\text{DEBUG}}$ bit in Configuration Words is managed automatically by device development tools including debuggers and programmers. For normal device operation, this bit should be maintained as a '1'.

7.0 INTERRUPTS

The interrupt feature allows certain events to preempt normal program flow. Firmware is used to determine the source of the interrupt and act accordingly. Some interrupts can be configured to wake the MCU from Sleep mode.

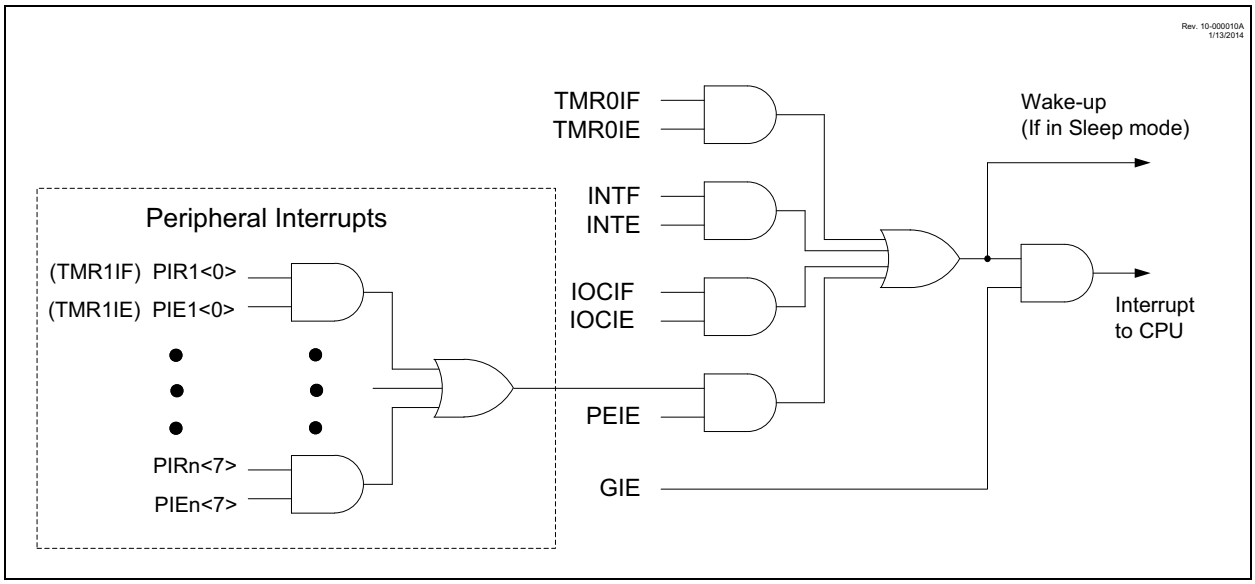
This chapter contains the following information for Interrupts:

- Operation
- Interrupt Latency
- Interrupts During Sleep
- INT Pin
- Automatic Context Saving

Many peripherals produce interrupts. Refer to the corresponding chapters for details.

A block diagram of the interrupt logic is shown in Figure 7-1.

FIGURE 7-1: INTERRUPT LOGIC



8.0 POWER-DOWN MODE (SLEEP)

The Power-Down mode is entered by executing a SLEEP instruction.

Upon entering Sleep mode, the following conditions exist:

1. WDT will be cleared but keeps running, if enabled for operation during Sleep.
2. $\overline{PD}$ bit of the STATUS register is cleared.
3. $\overline{TO}$ bit of the STATUS register is set.
4. CPU clock is disabled.
5. 31 kHz LFINTOSC is unaffected and peripherals that operate from it may continue operation in Sleep.
6. Timer1 and peripherals that operate from Timer1 continue operation in Sleep when the Timer1 clock source selected is:
   - LFINTOSC
   - T1CKI
7. ADC is unaffected, if the dedicated FRC oscillator is selected.
8. I/O ports maintain the status they had before SLEEP was executed (driving high, low or high-impedance).
9. Resets other than WDT are not affected by Sleep mode.

Refer to individual chapters for more details on peripheral operation during Sleep.

To minimize current consumption, the following conditions should be considered:

- I/O pins should not be floating
- External circuitry sinking current from I/O pins
- Internal circuitry sourcing current from I/O pins
- Current draw from pins with internal weak pull-ups
- Modules using 31 kHz LFINTOSC
- CWG module using HFINTOSC

I/O pins that are high-impedance inputs should be pulled to V_{DD} or V_{SS} externally to avoid switching currents caused by floating inputs.

Examples of internal circuitry that might be sourcing current include the FVR module. See **Section 14.0 "Fixed Voltage Reference (FVR)"** for more information on this module.

8.1 Wake-up from Sleep

The device can wake-up from Sleep through one of the following events:

1. External Reset input on $\overline{MCLR}$ pin, if enabled
2. BOR Reset, if enabled
3. POR Reset
4. Watchdog Timer, if enabled
5. Any external interrupt
6. Interrupts by peripherals capable of running during Sleep (see individual peripheral for more information)

The first three events will cause a device Reset. The last three events are considered a continuation of program execution. To determine whether a device Reset or wake-up event occurred, refer to **Section 6.12 "Determining the Cause of a Reset"**.

When the SLEEP instruction is being executed, the next instruction (PC + 1) is prefetched. For the device to wake-up through an interrupt event, the corresponding interrupt enable bit must be enabled. Wake-up will occur regardless of the state of the GIE bit. If the GIE bit is disabled, the device continues execution at the instruction after the SLEEP instruction. If the GIE bit is enabled, the device executes the instruction after the SLEEP instruction, the device will then call the Interrupt Service Routine. In cases where the execution of the instruction following SLEEP is not desirable, the user should have a NOP after the SLEEP instruction.

The WDT is cleared when the device wakes up from Sleep, regardless of the source of wake-up.

8.1.1 WAKE-UP USING INTERRUPTS

When global interrupts are disabled (GIE cleared) and any interrupt source has both its interrupt enable bit and interrupt flag bit set, one of the following will occur:

- If the interrupt occurs **before** the execution of a SLEEP instruction
  - SLEEP instruction will execute as a NOP.
  - WDT and WDT prescaler will not be cleared
  - $\overline{TO}$ bit of the STATUS register will not be set
  - $\overline{PD}$ bit of the STATUS register will not be cleared.
- If the interrupt occurs **during or after** the execution of a SLEEP instruction
  - SLEEP instruction will be completely executed
  - Device will immediately wake-up from Sleep
  - WDT and WDT prescaler will be cleared
  - $\overline{TO}$ bit of the STATUS register will be set
  - $\overline{PD}$ bit of the STATUS register will be cleared

Even if the flag bits were checked before executing a SLEEP instruction, it may be possible for flag bits to become set before the SLEEP instruction completes. To determine whether a SLEEP instruction executed, test the $\overline{PD}$ bit. If the $\overline{PD}$ bit is set, the SLEEP instruction was executed as a NOP.

10.2.2 FLASH MEMORY UNLOCK SEQUENCE

The unlock sequence is a mechanism that protects the Flash program memory from unintended self-write programming or erasing. The sequence must be executed and completed without interruption to successfully complete any of the following operations:

- Row Erase
- Load program memory write latches
- Write of program memory write latches to program memory
- Write of program memory write latches to user IDs

The unlock sequence consists of the following steps:

1. Write 55h to PMCON2
2. Write AAh to PMCON2
3. Set the WR bit in PMCON1
4. NOP instruction
5. NOP instruction

Once the WR bit is set, the processor will always force two NOP instructions. When an Erase Row or Program Row operation is being performed, the processor will stall internal operations (typical 2 ms), until the operation is complete and then resume with the next instruction. When the operation is loading the program memory write latches, the processor will always force the two NOP instructions and continue uninterrupted with the next instruction.

Since the unlock sequence must not be interrupted, global interrupts should be disabled prior to the unlock sequence and re-enabled after the unlock sequence is completed.

FIGURE 10-3: FLASH PROGRAM MEMORY UNLOCK SEQUENCE FLOWCHART

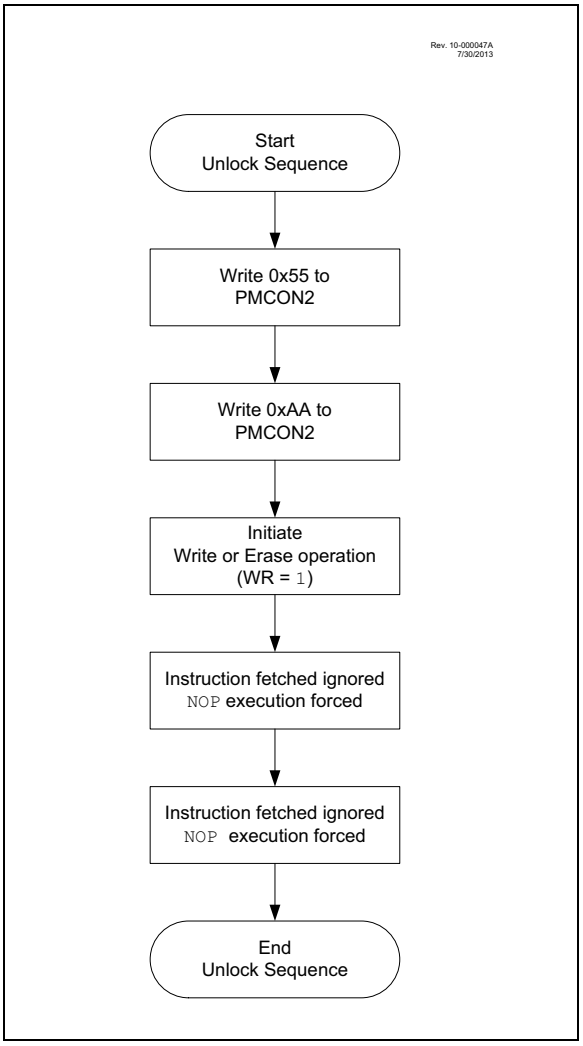
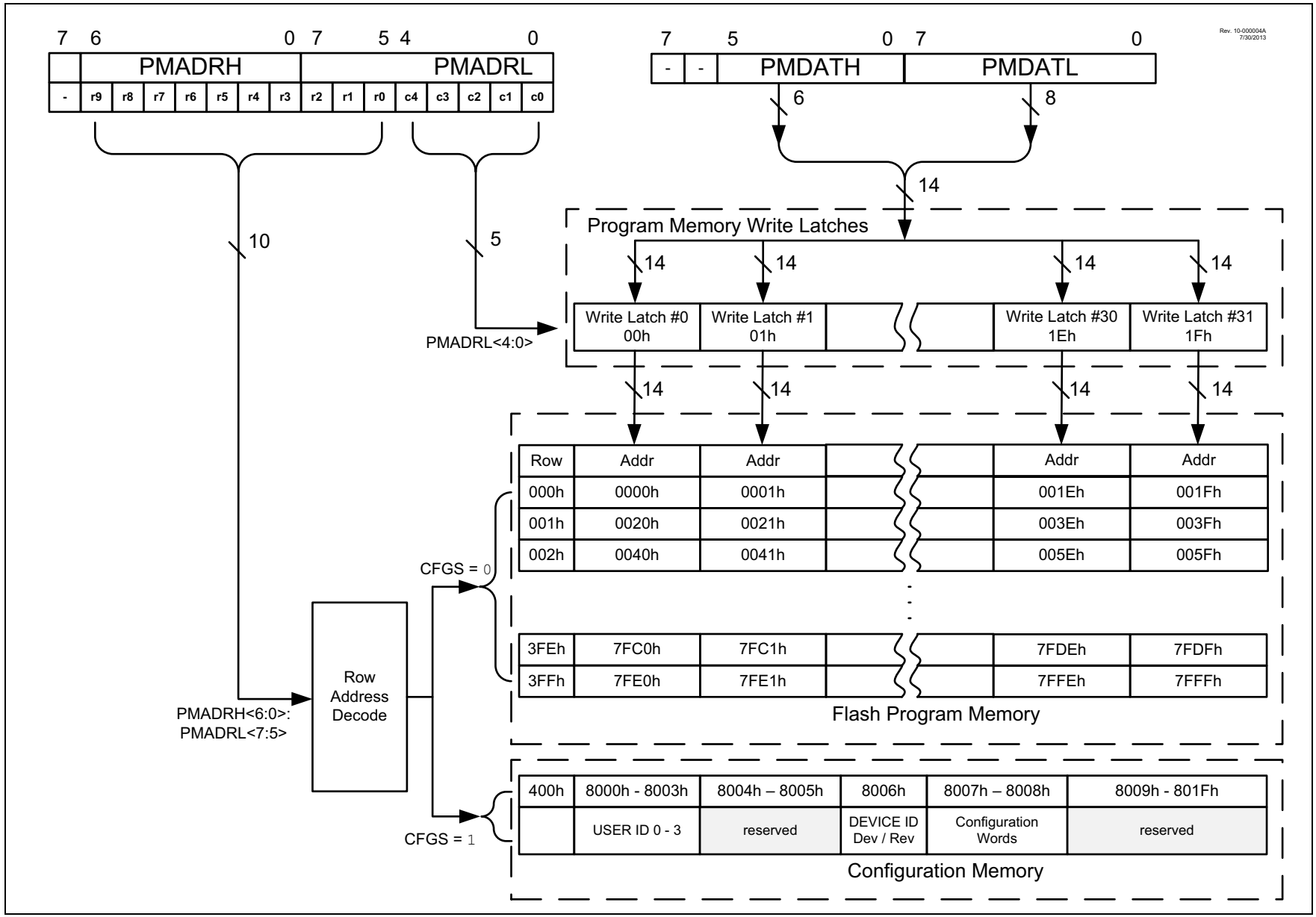


FIGURE 10-5: BLOCK WRITES TO FLASH PROGRAM MEMORY WITH 32 WRITE LATCHES

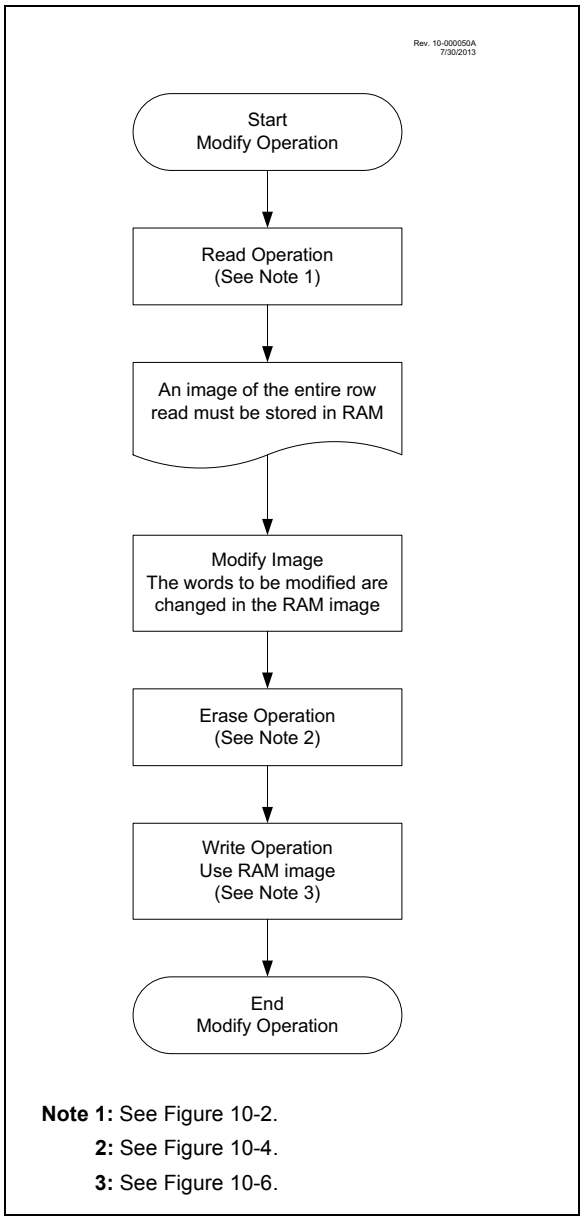


10.3 Modifying Flash Program Memory

When modifying existing data in a program memory row, and data within that row must be preserved, it must first be read and saved in a RAM image. Program memory is modified using the following steps:

1. Load the starting address of the row to be modified.
2. Read the existing data from the row into a RAM image.
3. Modify the RAM image to contain the new data to be written into program memory.
4. Load the starting address of the row to be rewritten.
5. Erase the program memory row.
6. Load the write latches with data from the RAM image.
7. Initiate a programming operation.

FIGURE 10-7: FLASH PROGRAM MEMORY MODIFY FLOWCHART



Note 1: See Figure 10-2.
2: See Figure 10-4.
3: See Figure 10-6.

REGISTER 11-14: ODCONB: PORTB OPEN DRAIN CONTROL REGISTER

R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	U-0	U-0	U-0	U-0
ODB7	ODB6	ODB5	ODB4	—	—	—	—
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-4 **ODB<7:4>:** PORTB Open-Drain Enable bits
For RB<7:4> pins, respectively
1 = Port pin operates as open-drain drive (sink current only)
0 = Port pin operates as standard push-pull drive (source and sink current)

bit 3-0 **Unimplemented:** Read as '0'

REGISTER 11-15: SLRCONB: PORTB SLEW RATE CONTROL REGISTER

R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	U-0	U-0	U-0	U-0
SLRB7	SLRB6	SLRB5	SLRB4	—	—	—	—
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-4 **SLRB<7:4>:** PORTB Slew Rate Enable bits
For RB<7:4> pins, respectively
1 = Port pin slew rate is limited
0 = Port pin slews at maximum rate

bit 3-0 **Unimplemented:** Read as '0'

REGISTER 11-16: INLVLB: PORTB INPUT LEVEL CONTROL REGISTER

R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	U-0	U-0	U-0	U-0
INLVLB7	INLVLB6	INLVLB5	INLVLB4	—	—	—	—
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-4 **INLVLB<7:4>:** PORTB Input Level Select bits
For RB<7:4> pins, respectively
1 = ST input used for port reads and interrupt-on-change
0 = TTL input used for port reads and interrupt-on-change

bit 3-0 **Unimplemented:** Read as '0'

15.0 TEMPERATURE INDICATOR MODULE

This family of devices is equipped with a temperature circuit designed to measure the operating temperature of the silicon die. The circuit's range of operating temperature falls between -40°C and +85°C. The output is a voltage that is proportional to the device temperature. The output of the temperature indicator is internally connected to the device ADC.

The circuit may be used as a temperature threshold detector or a more accurate temperature indicator, depending on the level of calibration performed. A one-point calibration allows the circuit to indicate a temperature closely surrounding that point. A two-point calibration allows the circuit to sense the entire range of temperature more accurately. Reference Application Note AN1333, "*Use and Calibration of the Internal Temperature Indicator*" (DS01333) for more details regarding the calibration process.

15.1 Circuit Operation

Figure 15-1 shows a simplified block diagram of the temperature circuit. The proportional voltage output is achieved by measuring the forward voltage drop across multiple silicon junctions.

Equation 15-1 describes the output characteristics of the temperature indicator.

EQUATION 15-1: V_{OUT} RANGES

High Range: $V_{OUT} = V_{DD} - 4V_T$

Low Range: $V_{OUT} = V_{DD} - 2V_T$

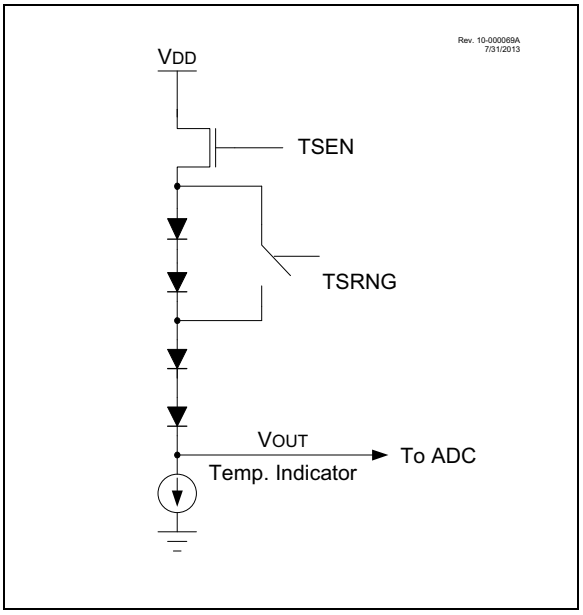
The temperature sense circuit is integrated with the Fixed Voltage Reference (FVR) module. See **Section 14.0 "Fixed Voltage Reference (FVR)"** for more information.

The circuit is enabled by setting the TSEN bit of the FVRCON register. When disabled, the circuit draws no current.

The circuit operates in either high or low range. The high range, selected by setting the TSRNG bit of the FVRCON register, provides a wider output voltage. This provides more resolution over the temperature range, but may be less consistent from part to part. This range requires a higher bias voltage to operate and thus, a higher V_{DD} is needed.

The low range is selected by clearing the TSRNG bit of the FVRCON register. The low range generates a lower voltage drop and thus, a lower bias voltage is needed to operate the circuit. The low range is provided for low voltage operation.

FIGURE 15-1: TEMPERATURE CIRCUIT DIAGRAM



15.2 Minimum Operating V_{DD}

When the temperature circuit is operated in low range, the device may be operated at any operating voltage that is within specifications.

When the temperature circuit is operated in high range, the device operating voltage, V_{DD}, must be high enough to ensure that the temperature circuit is correctly biased.

Table 15-1 shows the recommended minimum V_{DD} vs. range setting.

TABLE 15-1: RECOMMENDED V_{DD} VS. RANGE

Min. V_{DD}, TSRNG = 1	Min. V_{DD}, TSRNG = 0
3.6V	1.8V

15.3 Temperature Output

The output of the circuit is measured using the internal Analog-to-Digital Converter. A channel is reserved for the temperature circuit output. Refer to **Section 16.0 "Analog-to-Digital Converter (ADC) Module"** for detailed information.

15.4 ADC Acquisition Time

To ensure accurate temperature measurements, the user must wait at least 200 μs after the ADC input multiplexer is connected to the temperature indicator output before the conversion is performed. In addition, the user must wait 200 μs between sequential conversions of the temperature indicator output.

17.0 5-BIT DIGITAL-TO-ANALOG CONVERTER (DAC) MODULE

The Digital-to-Analog Converter supplies a variable voltage reference, ratiometric with the input source, with 32 selectable output levels.

The positive input source (VSOURCE+) of the DAC can be connected to:

- External VREF+ pin
- VDD supply voltage
- FVR_buffer1

The negative input source (VSOURCE-) of the DAC can be connected to:

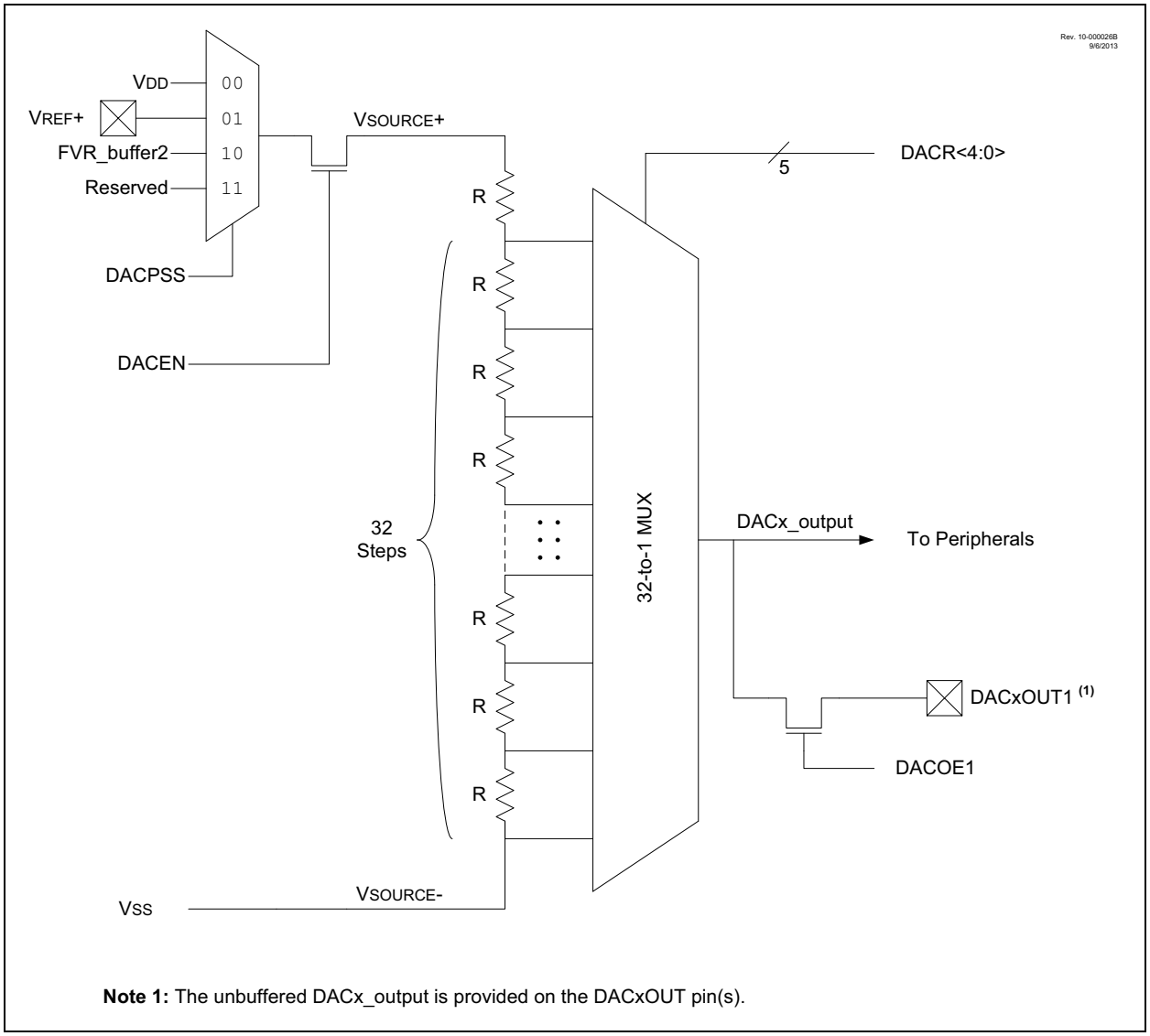
- Vss

The output of the DAC (DACx_output) can be selected as a reference voltage to the following:

- Comparator positive input
- ADC input channel
- DACxOUT1 pin

The Digital-to-Analog Converter (DAC) can be enabled by setting the DACEN bit of the DACxCON0 register.

FIGURE 17-1: DIGITAL-TO-ANALOG CONVERTER BLOCK DIAGRAM



Note 1: The unbuffered DACx_output is provided on the DACxOUT pin(s).

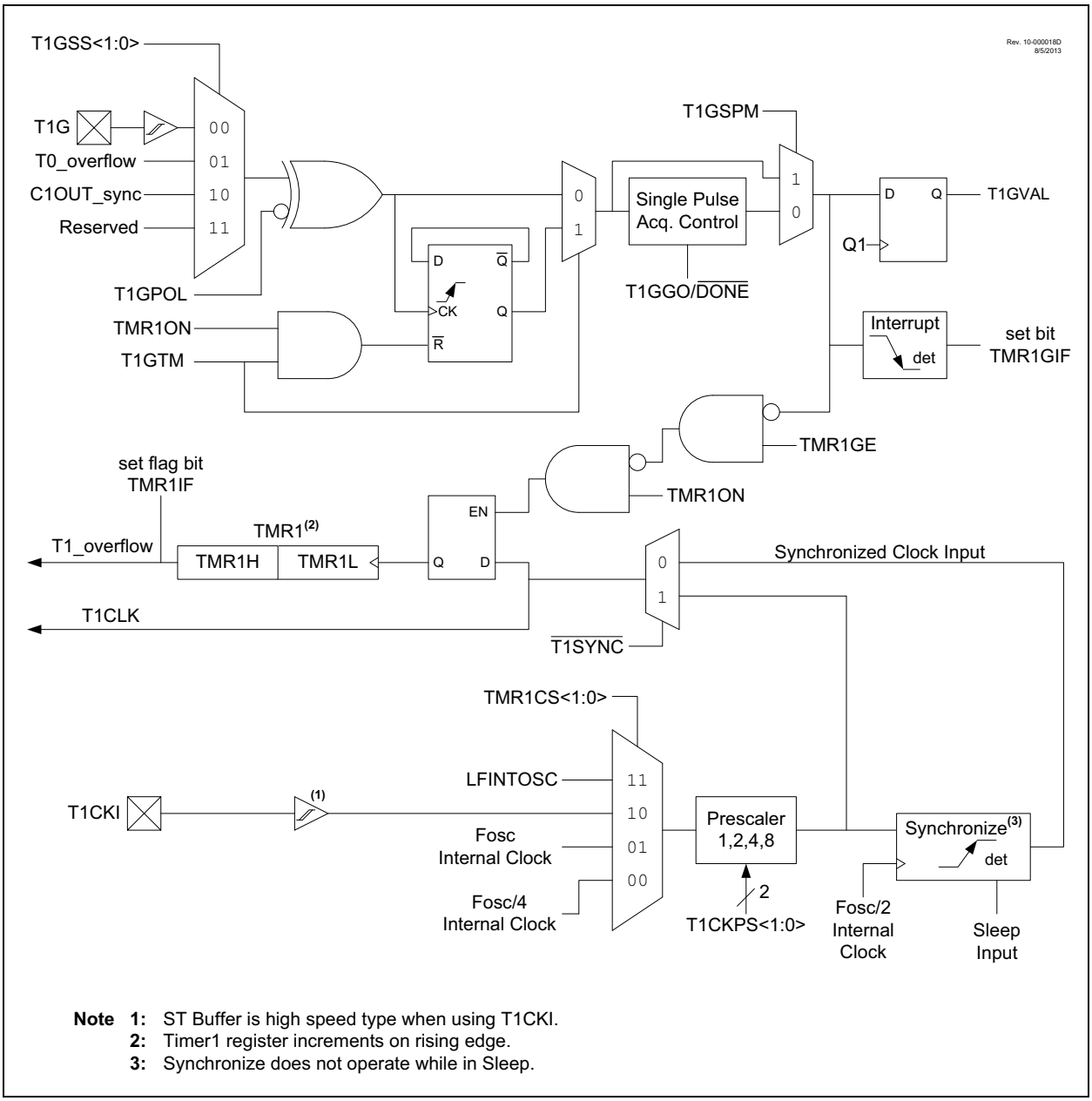
20.0 TIMER1 MODULE WITH GATE CONTROL

The Timer1 module is a 16-bit timer/counter with the following features:

- 16-bit timer/counter register pair (TMR1H:TMR1L)
- Programmable internal or external clock source
- 2-bit prescaler
- Optionally synchronized comparator out
- Multiple Timer1 gate (count enable) sources
- Interrupt on overflow
- Wake-up on overflow (external clock, Asynchronous mode only)
- ADC Auto-Conversion Trigger(s)
- Selectable Gate Source Polarity
- Gate Toggle mode
- Gate Single-Pulse mode
- Gate Value Status
- Gate Event Interrupt

Figure 20-1 is a block diagram of the Timer1 module.

FIGURE 20-1: TIMER1 BLOCK DIAGRAM



Note 1: ST Buffer is high speed type when using T1CKI.
2: Timer1 register increments on rising edge.
3: Synchronize does not operate while in Sleep.

TABLE 22-3: BAUD RATE FORMULAS

Configuration Bits			BRG/EUSART Mode	Baud Rate Formula
SYNC	BRG16	BRGH		
0	0	0	8-bit/Asynchronous	FOSC/[64 (n+1)]
0	0	1	8-bit/Asynchronous	FOSC/[16 (n+1)]
0	1	0	16-bit/Asynchronous	
0	1	1	16-bit/Asynchronous	FOSC/[4 (n+1)]
1	0	x	8-bit/Synchronous	
1	1	x	16-bit/Synchronous	

Legend: x = Don't care, n = value of SPBRGH, SPBRGL register pair.

TABLE 22-4: SUMMARY OF REGISTERS ASSOCIATED WITH THE BAUD RATE GENERATOR

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
BAUDCON	ABDOVF	RCIDL	—	SCKP	BRG16	—	WUE	ABDEN	204
RCSTA	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	203
SPBRGL	BRG<7:0>								205*
SPBRGH	BRG<15:8>								205*
TXSTA	CSRC	TX9	TXEN	SYNC	SENDB	BRGH	TRMT	TX9D	202

Legend: — = unimplemented location, read as '0'. Shaded cells are not used for the Baud Rate Generator.

* Page provides register information.

FIGURE 23-4: STANDARD PWM MODE TIMING DIAGRAM

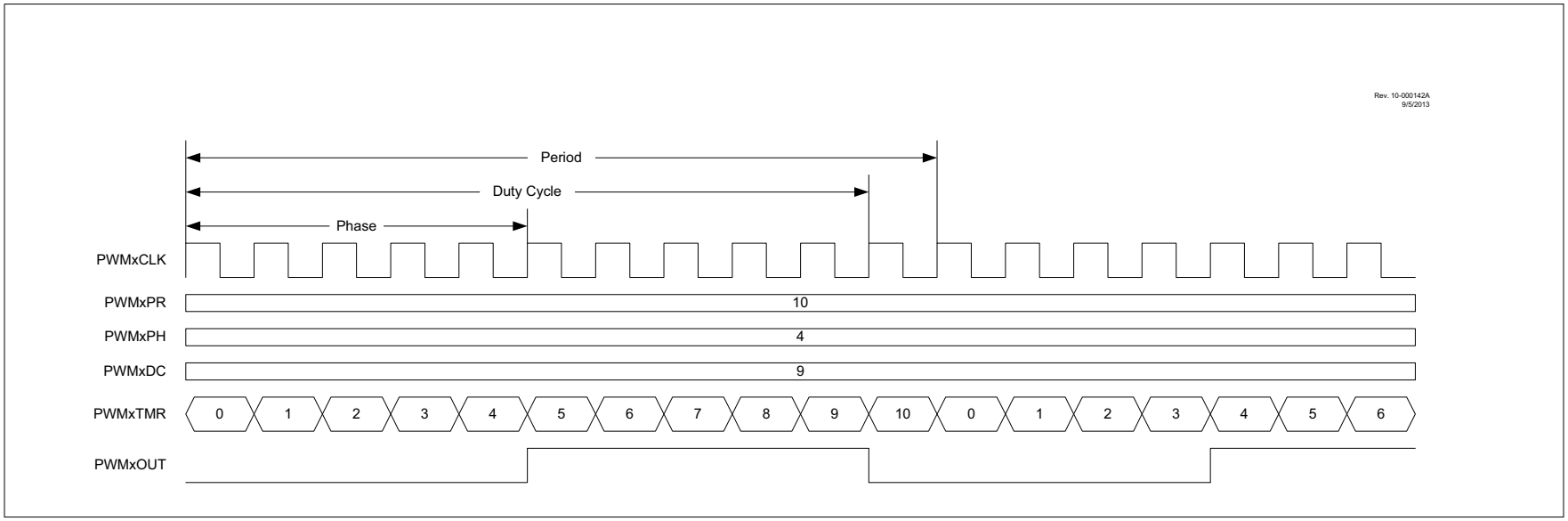


FIGURE 23-5: SET ON MATCH PWM MODE TIMING DIAGRAM

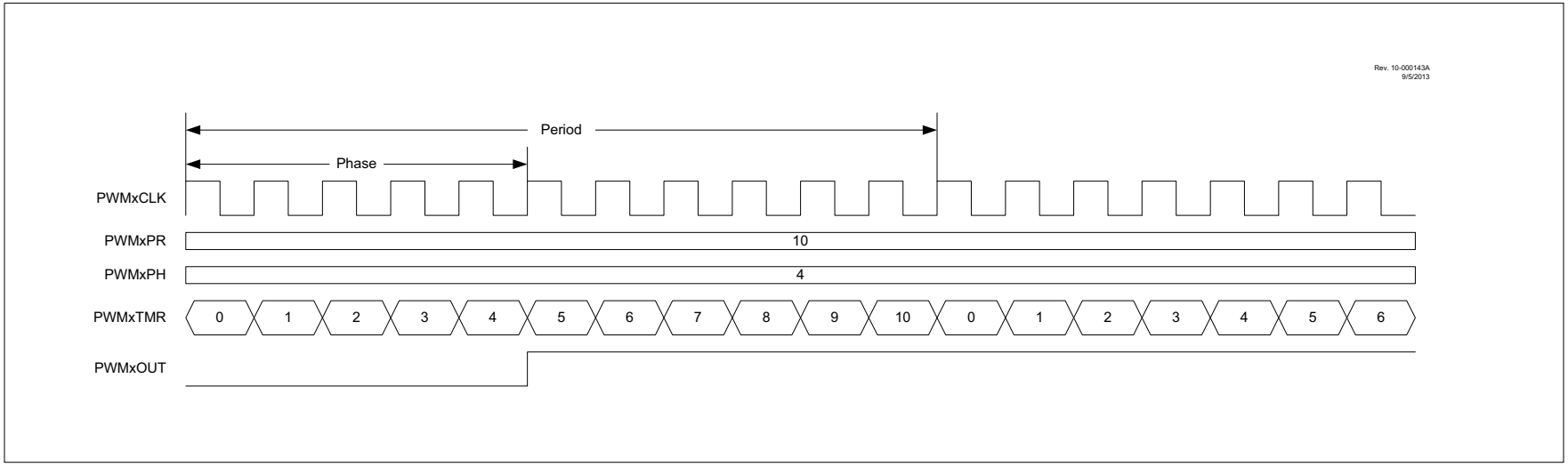
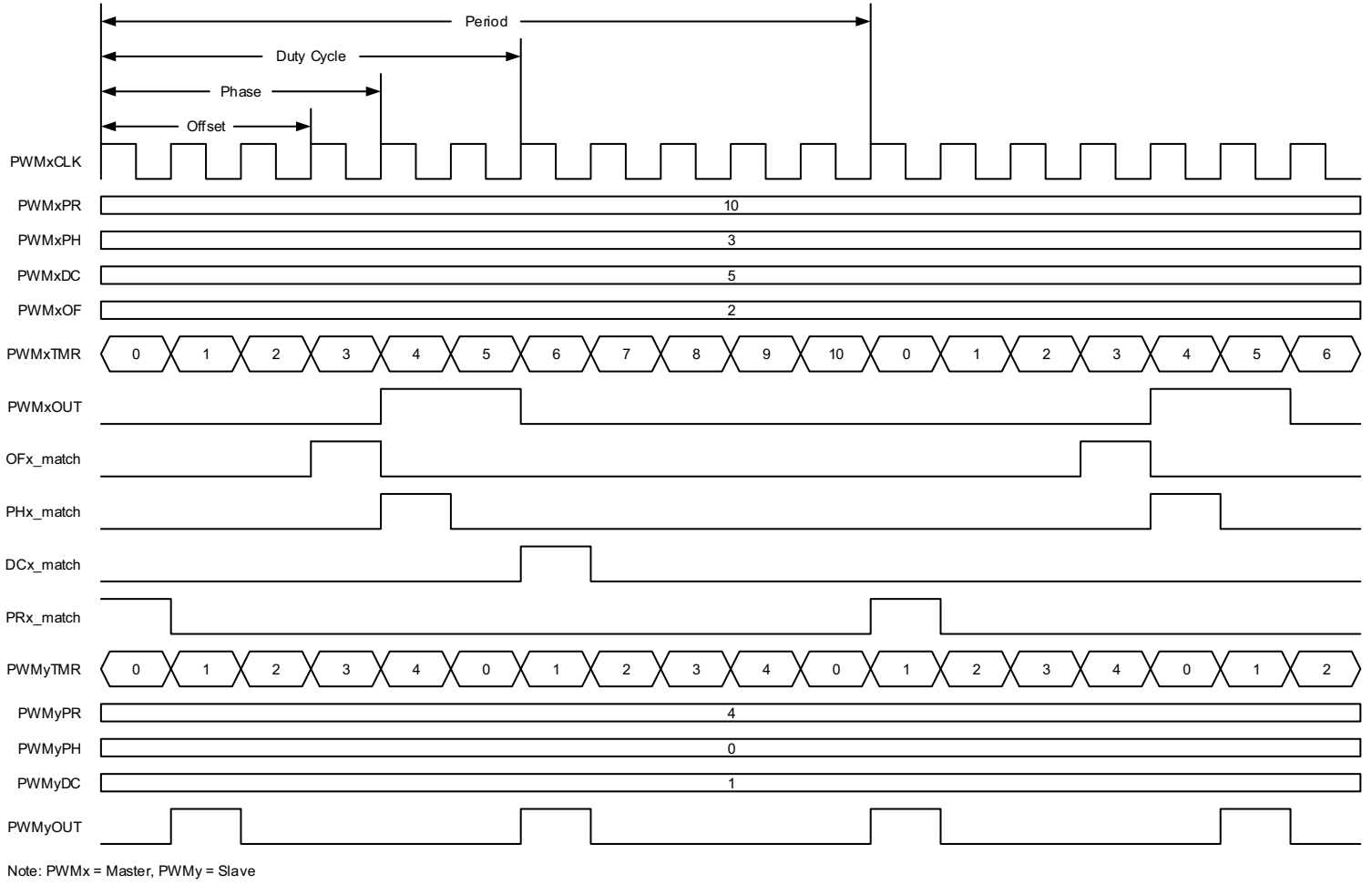


FIGURE 23-8: INDEPENDENT RUN MODE TIMING DIAGRAM



Note: PWMx = Master, PWMy = Slave

REGISTER 23-7: PWMxPHH: PWMx PHASE COUNT HIGH REGISTER

R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
PH<15:8>							
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-0 **PH<15:8>**: PWM Phase High bits
Upper eight bits of PWM phase count

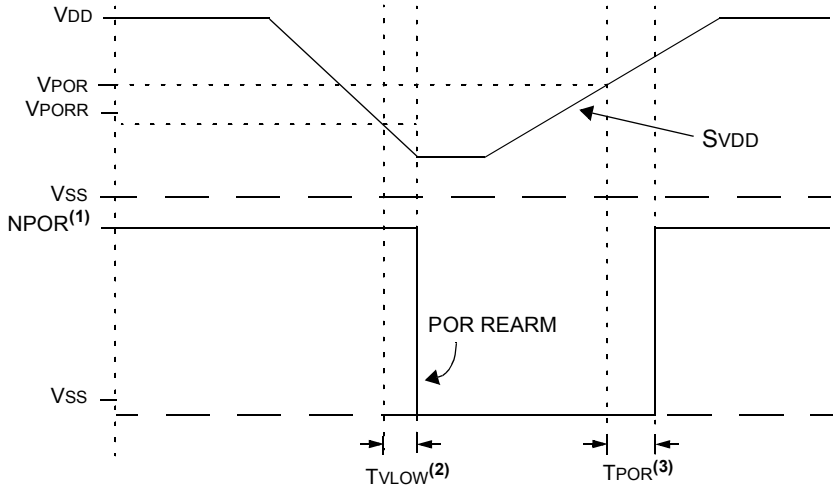
REGISTER 23-8: PWMxPHL: PWMx PHASE COUNT LOW REGISTER

R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
PH<7:0>							
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-0 **PH<7:0>**: PWM Phase Low bits
Lower eight bits of PWM phase count

FIGURE 27-3: POR AND POR REARM WITH SLOW RISING VDD



Note 1: When NPOR is low, the device is held in Reset.
2: TPOR 1 μs typical.
3: TVLOW 2.7 μs typical.

29.0 DEVELOPMENT SUPPORT

The PIC® microcontrollers (MCU) and dsPIC® digital signal controllers (DSC) are supported with a full range of software and hardware development tools:

- Integrated Development Environment
  - MPLAB® X IDE Software
- Compilers/Assemblers/Linkers
  - MPLAB XC Compiler
  - MPASM™ Assembler
  - MPLINK™ Object Linker/ MPLIB™ Object Librarian
  - MPLAB Assembler/Linker/Librarian for Various Device Families
- Simulators
  - MPLAB X SIM Software Simulator
- Emulators
  - MPLAB REAL ICE™ In-Circuit Emulator
- In-Circuit Debuggers/Programmers
  - MPLAB ICD 3
  - PICkit™ 3
- Device Programmers
  - MPLAB PM3 Device Programmer
- Low-Cost Demonstration/Development Boards, Evaluation Kits and Starter Kits
- Third-party development tools

29.1 MPLAB X Integrated Development Environment Software

The MPLAB X IDE is a single, unified graphical user interface for Microchip and third-party software, and hardware development tool that runs on Windows®, Linux and Mac OS® X. Based on the NetBeans IDE, MPLAB X IDE is an entirely new IDE with a host of free software components and plug-ins for high-performance application development and debugging. Moving between tools and upgrading from software simulators to hardware debugging and programming tools is simple with the seamless user interface.

With complete project management, visual call graphs, a configurable watch window and a feature-rich editor that includes code completion and context menus, MPLAB X IDE is flexible and friendly enough for new users. With the ability to support multiple tools on multiple projects with simultaneous debugging, MPLAB X IDE is also suitable for the needs of experienced users.

Feature-Rich Editor:

- Color syntax highlighting
- Smart code completion makes suggestions and provides hints as you type
- Automatic code formatting based on user-defined rules
- Live parsing

User-Friendly, Customizable Interface:

- Fully customizable interface: toolbars, toolbar buttons, windows, window placement, etc.
- Call graph window

Project-Based Workspaces:

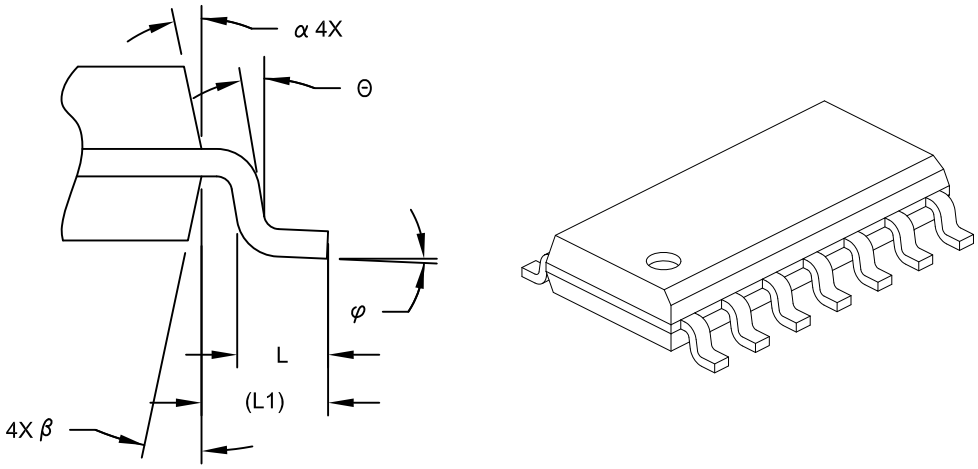
- Multiple projects
- Multiple tools
- Multiple configurations
- Simultaneous debugging sessions

File History and Bug Tracking:

- Local file history feature
- Built-in support for Bugzilla issue tracker

14-Lead Plastic Small Outline (SL) - Narrow, 3.90 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



VIEW C

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		14	
Pitch	e		1.27 BSC	
Overall Height	A	-	-	1.75
Molded Package Thickness	A2	1.25	-	-
Standoff §	A1	0.10	-	0.25
Overall Width	E		6.00 BSC	
Molded Package Width	E1		3.90 BSC	
Overall Length	D		8.65 BSC	
Chamfer (Optional)	h	0.25	-	0.50
Foot Length	L	0.40	-	1.27
Footprint	L1		1.04 REF	
Lead Angle	Θ	0°	-	-
Foot Angle	φ	0°	-	8°
Lead Thickness	c	0.10	-	0.25
Lead Width	b	0.31	-	0.51
Mold Draft Angle Top	α	5°	-	15°
Mold Draft Angle Bottom	β	5°	-	15°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic
3. Dimension D does not include mold flash, protrusions or gate burrs, which shall not exceed 0.15 mm per end. Dimension E1 does not include interlead flash or protrusion, which shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
   REF: Reference Dimension, usually without tolerance, for information purposes only.
5. Datums A & B to be determined at Datum H.

Microchip Technology Drawing No. C04-065C Sheet 2 of 2

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

PART NO.	[X](1)	-	X	/XX	XXX
Device	Tape and Reel Option		Temperature Range	Package	Pattern

Device:	PIC16LF1574, PIC16F1574, PIC16LF1575, PIC16F1575 PIC16LF1578, PIC16F1578, PIC16LF1579, PIC16F1579	
Tape and Reel Option:	Blank T	= Standard packaging (tube or tray) = Tape and Reel(1)
Temperature Range:	I E	= -40°C to +85°C (Industrial) = -40°C to +125°C (Extended)
Package:(2)	GZ JQ P SL SO SS ST	= UQFN, 20-Lead (4x4x0.5mm) = UQFN, 16-Lead (4x4x0.5mm) = Plastic DIP = SOIC, 14-Lead = SOIC, 20-Lead = SSOP, 20-Lead = TSSOP, 14-Lead
Pattern:	QTP, SQTP, Code or Special Requirements (blank otherwise)	

Examples:

a) PIC16LF1578T - I/SO
Tape and Reel,
Industrial temperature,
SOIC package

b) PIC16F1575 - I/P
Industrial temperature
PDIP package

c) PIC16LF1574-E/JQ
Extended Temperature
UQFN Package

Note 1: Tape and Reel identifier only appears in the catalog part number description. This identifier is used for ordering purposes and is not printed on the device package. Check with your Microchip Sales Office for package availability with the Tape and Reel option.

2: For other small form-factor package availability and marking information, please visit www.microchip.com/packaging or contact your local sales office.